

AI

Product Roadmap



Embedded Mainboard & SBC

Embedded Fanless PC

IP65/66/67/69K Panel PC / Box PC



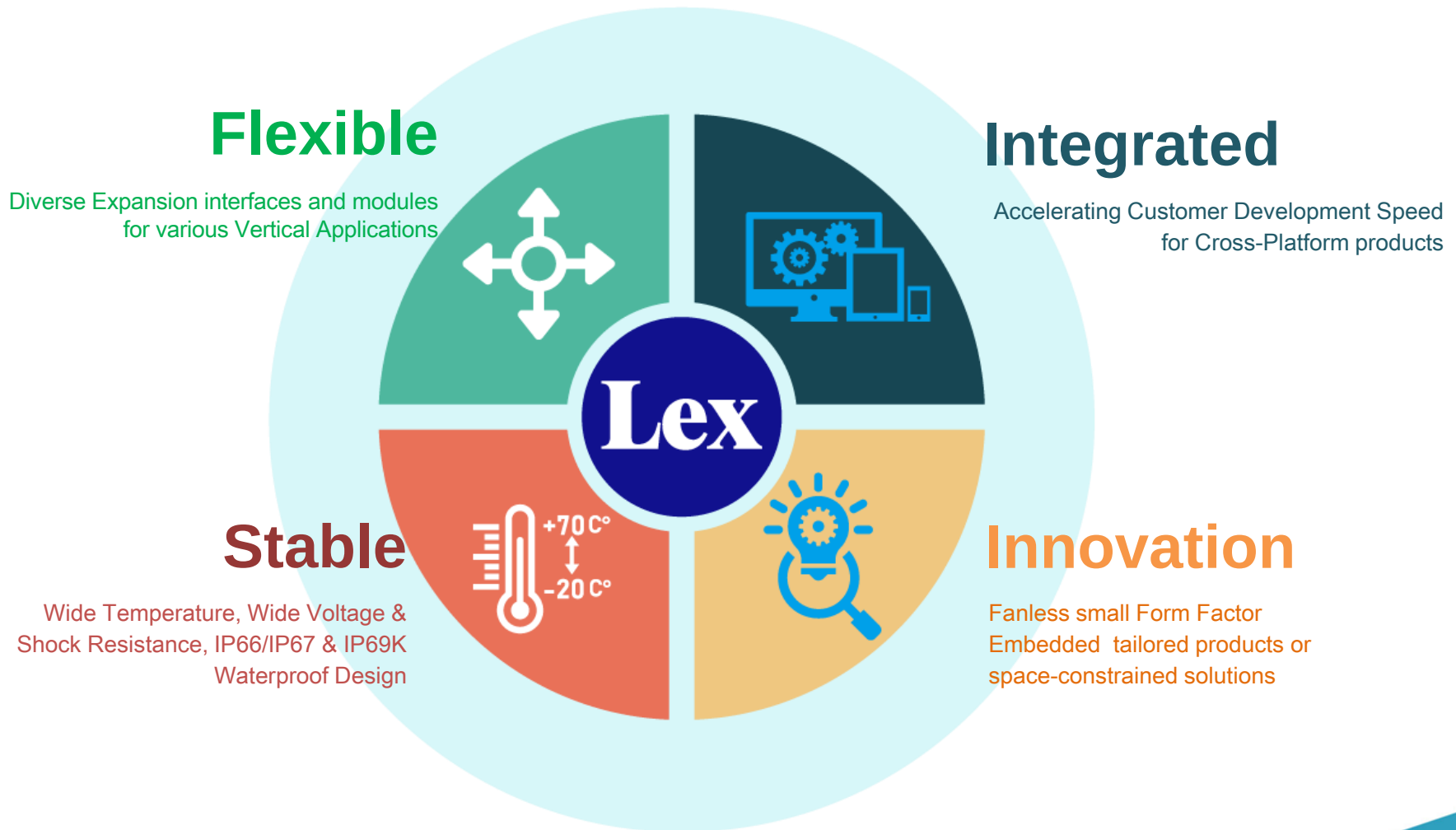
Lex SYSTEM®

2025 Q3

Contents

- LEX System Features & Advantages
- Embedded Solution Overview
- Embedded Solution Case Study
- Product Highlights
- Product Development Timeline
- Product long term supply
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Features & Advantages



LEX SYSTEM – Embedded Solution

LEX offers design and manufacturing of industrial motherboards, industrial computers, expansion boards, and customized industrial computers, including edge computing systems and AI intelligent application platforms. Our in-house developed products cover four major categories:



Total : 83 pcs

1 Embedded IPC Board

- Femto-ITX 1.8" : 3pcs
- 3.5"SBC : 30 pcs
- Computer On Module : 5 pcs
- UPS board : 4 pcs *
- double counting with SBC
- Pico-ITX 2.5" : 27 pcs
- 5 ¼ " (200 x 150mm) : 4 pcs
- CPU board : 3 pcs
- ARM based : 7pcs



2 Customized Motherboard & Chassis

Innovating Research & Integration Services for
Global OEM/ODM and System Integrators

• Applications



AI / Visual Analytics



Smart Manufacturing /
Machine Vision



IoT / IIoT



Smart Healthcare/
AI Medical Imaging



Smart Transportation &
Railways



Maritime Shipping
& Navigation



Defense / Military
Robust Computers



Edge Computing
Edge Gateway Control



Networking/
Communication Equipment

LEX SYSTEM – Embedded Solution



3 Fanless Rugged Panel PC, Fanless Embedded Systems, Servers



4 Expansion Boards/Cards & Related Accessories

Fanless Rugged Panel PC



•SUPER series (7"/10.1"/10.4"/15")



•VITA series (10.1"/15"/21.5"/23.8")



•Slim series (8.4"/10.2"/15.1"/17")



•SHARK IP66/67 **waterproof** (10.1"/13.3")



•STAR IP66/67 **waterproof** (10.4"/12.1"/15.1")

•**Stainless** IP66/IP67/IP69K **waterproof**

(10.4"/15.1"/19")

Fanless Embedded System



•Rugged /Waterproof System



•In-vehicle System

•DIN Rail System



•1U server

•AI image Analysis & Machine Vision

•Ultra Compact / Compact System

•High-Speed Ethernet Network Card / PoE / Fiber Card

•4G / 5G / WiFi / Bluetooth Module

•Video Capture Card

•USB / SIM / COM / Display Conversion Card

•M.2 / eIO Expansion Card

•Storage Card

•Digital IO Card

•Carriers and Converter Boards

•Power Boards and Charger Modules

Embedded Solution— Case Study



Spain
Intelligent Transportation
Surveillance System



China
Highway ETC smarting
billing system



Germany
3D Surgery Navigation



China
Servotronics EtherCAT
Robot Motion Control

Embedded Solution— Case Study



Kiosk-Self Service
Harsh outdoor Panel PC
for Winter Olympics



Video Analysis
Metro Real-time
Surveillance System



Poland
Railway in-train
communication



Netherlands
Fleet management

2025 Q3 Product Highlights

CI870CW-Industrial SBC



Intel® 15th Gen Core™ Ultra 7/5
(Arrow Lake-S) Series processors
DP/HDMI@/Type C, LVDS/eDP
2 x DDR5 SODIMM ,Max 64GB
5 x Intel 2.5 GbE, 4 x USB 3.2, 4 x USB 2.0
1 x PCIe , 3 x M.2 ,1 x Nano SIM , HD Audio
10 x COM, 8 DI / 8DO

3I140HW-3.5" SBC



Intel® 14th/15th Gen
Meteor Lake-U/H /Arrow Lake-U/H
Core Ultra CPU
DP, HDMI @, LVDS /DP
2 x DDR5 SODIMM Max 64GB
3 x Intel 2.5 GbE, 4 x USB 3.2, 3 x USB 2.0
3 x M.2 ,1 x Nano SIM, HD Audio
4 x COM, 4DI / 4DO ,2 X MIPI-CSI

3I140DW-3.5" SBC



Intel® 14th/15th Gen
Meteor Lake-U/H /Arrow Lake-U/H
Core Ultra CPU
DP, HDMI @, LVDS
2 x DDR5 SODIMM Max 64GB
5 x Intel 2.5 GbE, 3 x USB 3.2, 3 x USB 2.0
3 x M.2 ,1 x Nano SIM , HD Audio
4 x COM, 4DI / 4DO

2I740DW-2.5" SBC



Intel® ATOM Amston Lake x7211/x7213 CPU
Onboard LPDDR5, 8GB / 16GB
DP,HDMI@
3 x Intel 2.5 GbE, 3 x USB 3.2, 2 x USB 2.0
2 x M.2 , 2 x COM, DC-IN 12V/24
90.8 x 76.25 mm

2I740CW-2.5" SBC



Intel® ATOM Amston Lake x7211/x7213 CPU
1 x SODIMM DDR5, Max 32GB
HDMI@, Type C , LVDS/eDP, Touch Screen
2 x Intel 2.5 GbE, 3 x USB 3.2, 4 x USB 2.0
2 x M.2 , 1 x Nano SIM, 2 x MIPI-CSI
4 x COM, HD Audio, 4DI/4DO
Wide Range DC-IN 9-36V
108 x 102 mm

Product Highlights (Embedded IPC Board)



2I130HW-2.5" Plus SBC
2I130DW-2.5" Plus SBC
3I130DW-3.5" Plus SBC
3I130TW-161x150 mm SBC



2I110D-2.5" Plus SBC
2I110AW-2.5" Plus SBC
3I110HW/BW-3.5" Plus SBC



3I470DW-155 x150 mm SBC



CI370D-217 x 185 mm SBC
CI371D-217 x 223 mm SBC
3I370DW-155 x130 mm SBC



2I810D-2.5" Plus SBC
3I810DW-3.5" Plus SBC
3I810HW/BW-3.5" Plus SBC



2I640PW-Compute on Module
2I640HL-2.5" Plus SBC with Hailo-8
2I640DW-2.5" Plus SBC
2I640CW-2.5" Plus SBC
2I640HW-2.5" Plus SBC
2I640SW-2.5" Plus SBC
3I640DW-3.5" SBC
3I640CW-3.5" SBC



2NOR01- 2.5" Plus carrier board
For Board for Edge AI solution with
NVIDIA® Jetson Orin™ Nano (Super)NX

ORIN-TW

Carrier Board for Railway solution with
NVIDIA® Jetson Orin™ Nano(Super) / NX

2NOR02- compact carrier board
For Edge AI solution with NVIDIA® Jetson
Orin™ Nano / NX

2NOR03- compact carrier board
For Edge AI solution with NVIDIA® Jetson
Orin™ Nano / NX



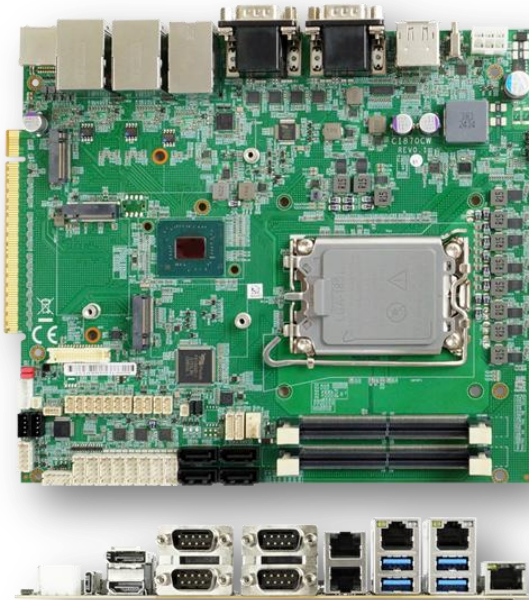
2N8MP01- 2.5" Plus SBC

NXP-HAI02- -carrier board with Hailo AI chip
For Edge AI solution with I.MX8M Plus CPU

NXP-HAI03 -carrier board with Hailo AI chip
For Edge AI solution with I.MX8M Plus CPU

2025 Q3 Product Development timeline

15th Gen Intel® Core™ Ultra CPU



CI870CW - EVT

Intel® 15th Gen Core™ Ultra 7/5 (Arrow Lake-S) Series processors

2 x DDR5 SODIMM, Max 64GB

Multiple Independent display:

1 x HDMI®, 1 x DP, 1 x eDP / LVDS, 1 x Type C

5 x Intel 2.5 GbE LAN, 4 x USB 3.2 Gen 1, 4 x USB 2.0

1 x M.2 M Key, 2 x M.2 B Key, 1 x Nano SIM, 1 x PCIe x16

10 x COM, 8DI / 8DO, Audio

TPM 2.0, SMBus, I2C, I2S

Wide Range DC IN+9~36V

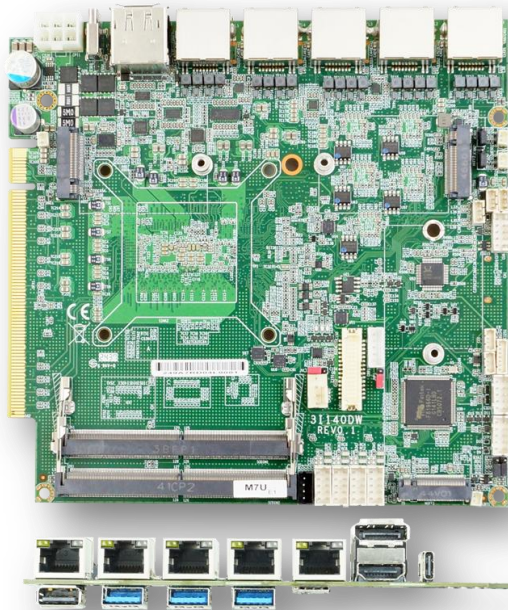
Dimension: LEX form factor (186 x 217 mm)



TWISTER(L)-CI870CW

2025 Q3 Product Development timeline

15th /14th Gen Intel® Core™ Ultra CPU



3I140DW - EVT

Intel 14th Gen Meteor lake-U/H Core Ultra CPU
Intel 15th Gen Arrow lake-U/H Core Ultra CPU
2 x DDR5 SODIMM Max 64GB
5 x Intel 2.5 GbE , 4 x COM
3 x USB 3.2 ; 3 x USB 2.0
1 x HDMI®, 1 x DP, 1 x Type C, LVDS/eDP(eDP for OEM),
1 x M.2 M key Type 3042 / 3080 (PCIe x 4), Support NVMe,
1 x M.2 B key Type 3042 / 3052 (USB 3.2 Gen 1x1/ USB 2.0),
1 x Nano SIM
1 x M.2 B key Type 3042 (PCIe x 2/ USB 2.0)
HD Audio with Amplifier
TPM 2.0
4 DI/ 4DO
1 x SATA
I2C, I2S, SMBus
PCIe x 16 golden finger with PCIe x 8, PCIe x 4 signal,
Wide Range DC IN+9~36V
Dimension: 150 x 155 mm



HAWK 3I140DW

2025 Q3 Product Development timeline



13th Gen Intel® Core™ Raptor Lake-P/U



2I130HW

Intel® 13th Gen Raptor Lake-U/P CPU
1 x DDR5 SODIMM (Max. 32GB)
HDMI, eDP, LVDS
2 x Intel 2.5 GbE, 4 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
HD Audio, 1 x Mini PCIe, 1 x M.2
108 x 102 mm



2I130DW

Intel® 13th Gen Raptor Lake-U CPU
1 x DDR5 SODIMM (Max. 32GB)
HDMI, eDP
4 x Intel 2.5 GbE, 3 x USB 3.2
4 x USB 2.0, 2 x COM, 4DI / 4DO,
2 x M.2, 1 x Nano SIM
108 x 102 mm



SKY 2 I130DW

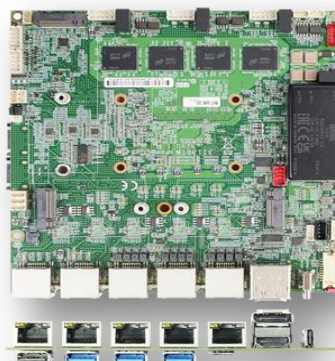


ROCK 2 I130DW



3I130DW

Intel® 13th Gen Raptor Lake-P / U CPU
2 x DDR5 SODIMM (Max. 64GB)
2 x HDMI, eDP, 1 x Type C DP ALT Mode
5 x Intel 2.5 GbE, 3 x USB 3.2, 5x USB 2.0
1 x Mini PCIe, 2 x M.2, 1 x Nano SIM
2 x COM, 4DI / 4DO
146 x 110 mm



3I130TW - EVT

Intel® 13th Gen Raptor Lake- U CPU
On-board LPDDR5 (16GB/32 GB)
HDMI, DP, eDP, 5 x Intel 2.5 GbE,
3 x USB 3.2, 3x USB 2.0, 3 x M.2,
1 x Nano SIM, 2 x ISO-COM, HD Audio
2 x ISO- CANBus, 4DI / 4DO, onboard NVMe
CPC -Ignition Delay on/off control
161 x 150 mm



HAWK 3I130TW (M12)



HAWK 3I130DW



SKY 3 I130DW

2025 Q3 Product Development timeline

NVIDIA Jetson Orin Nano(Super)/ NX SOM Carrier Board

JETSON
Orin™ NX

JETSON
Orin™ Nano



ORIN-TW

1 x DP, 5 x GbE (1 + 4 x PoE)
1 x USB 3.1 Type C ; 2 x USB 3.1 Type A ; 1x USB 2.0
Mic-in / Line-out ; AMP 2W, 2 x SATA
2 x Isolated RS232 / RS422 / RS485, 1 x Isolated CANBus
1 x M.2 M key, 4 x M.2 B key, 1 x M.2 E Key, 1 x Nano SIM
2 x MIPI CSI, SPI, I²S, 3 x I²C, 8DI / 8 DO,
ISO Wide Range +9~36V, CPC-Ignition on/off delay control
Dimension: 186 x 166 mm

CPU Board:

NVIDIA Jetson NX: 8 / 16GB LPDDR5, 70 / 100 TOPs
NVIDIA Jetson Nano(Super): 4 / 8GB LPDDR5, 20 / 40 TOPs
AI Accelerator: NVIDIA® Jetson Orin™ Nano(Super) / Orin™ NX



HAWK ORIN-TW



Back Panel
Optional M12 GbE I/O
Optional Anti-Vibration kit

Front Panel
Optional Mobile Rack

2NOR01 - EVT

1 x HDMI , 2 x 2.5GbE, 1 x GbE
4 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG), 1 x USB 2.0
Mic-in / Line-out ; AMP 2W
2 x RS232 (Option RS422), 1 x CANBus
1 x M.2 M key 2 x M.2 B key, 1 x SIM, 4DI / 4DO
Internal wafer: SPI, I2S, I2C, USB 2.0



ROCK 2NOR01



SKY 2NOR01

2NOR02

1 x HDMI®, 1 x GbE
8 x USB 3.1, 1 x Type C USB 3.1
/ 2.0 (OTG), 1 x USB 2.0
1 x RS232 (OEM to RS422)
1 x M.2 M key, 1 x M.2 B key,
URAT, I2S, 2 x I2C



PALM -2NOR02

2NOR03

1 x HDMI®, 1 x GbE, 1 x 2.5GbE
2 x USB 3.1, 1 x Type C USB 3.1 / 2.0 (OTG)
1 x RS232 (OEM Option RS422)
1 x M.2 M key, 1 x M.2 B key
Internal wafer: 2 x MIPI CSI, URAT, 2 x I2C

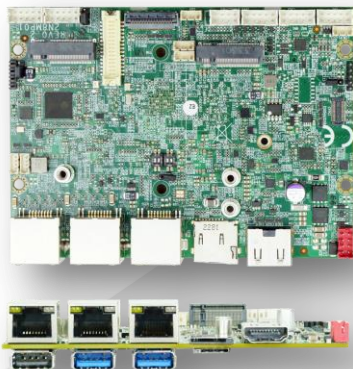


PALM - 2NOR03

2025 Q3 Product Development timeline



NXP i.MX8M Plus /ARM Cortex-A53



2N8MP01 - EVT

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 + M7 CPU
LPDDR4, 4GB / 8GB
Independent display: 1 x HDMI, LVDS, 1 x MIPI Display
3 x GbE LAN, 2 x USB 3.0, 3 x USB 2.0
2 x COM, 3 x M.2, 1 x Nano SIM
4DI / 4DO, 1 x MIPI (CSI), 1 x CANBus
115.4 x 84.5 mm

NET-II 2N8MP01



PALM-NEX001 - EVT

NXP i.MX8M Plus (Quad core)
ARM Cortex A53 CPU
LPDDR4, 8GB (NEX-8MP)
32GB eMMC 5.1 (NEX-8MP),
expandable to 256GB
HDMI ; 2 x GbE ; 2 x USB 3.0 / 2.0
1 x Micro SD, 1 x RS232, 1 x RS485
DC input : +5V
71.4W x 71.4D x 29.5H mm



MINI NXP-HAI02



MINI NXP-HAI02

MINI-NXP-HAI02

Compact Edge AI Box with Hailo-8™ AI processor



NXP-HAI02 Back



NXP-HAI02



NXP-HAI03

With NEX-8MP computer on module

NXP i.MX8M Plus (Quad core) ARM Cortex-A53
processor up to 1.8 GHz (NEX-8MP)
LPDDR4, 8GB (NEX-8MP)
32-256GB eMMC 5.1 (NEX-8MP)
Mini HDMI, 1 x USB 3.0 Type C
1 x GbE(M12) or 2 x RJ45 ;
1 x USB 3.0 Type A, 1 x Micro SD,
M8 Connector: DC Power, LAN, DI/DO RS485
Wide Range DC-IN +9-24V
Dimension: 66W x 94D x 30.8H mm

2025 Q3 Product Development timeline



Intel® Elkhart Lake ATOM /Celeron processor



2I640PW - EVT

Pico Express Computer on Module

Intel® Elkhart Lake ATOM® x6413E / J6412 CPU
On Board LPDDR4 4GB or 8GB
Independent display: 1 x HDMI, 1 x LVDS, 1 x VGA
2 x Intel 2.5 GbE LAN, 2 x USB 3.0, 5 x USB 2.0
4 x COM, 1 x Mini PCIe, 1 x M.2
1 x PCIe x2 (Pico-Express)
Touch Screen, HD Audio, 4DI / 4DO
102 X 85 mm



DK008 - EVT

Evaluation Board for 2I640PW

I/O: 1 x HDMI, 2 x RJ45, 2 x USB 3.0, 2 x USB 2.0
4 x COM, 1 x Mini PCIe, 1 x M.2, 1 x PCIe x1,
4DI / 4DO, Wide Range DC -IN
104 x 146 mm



DM003 - EVT

Evaluation Board for 2I640PW

2 x GbE (M12), 4 x USB (M12 x 2), PWR LED, 4 x
COM (M12 x 4), 1 x VGA (M12), 1 x mini HDMI®, 1
x AUDIO (M12), 1 x DC-IN (M12), 1 x SMBUS / I2C /
SPI (M12), 1 x SIM holder, 1 x USB 3.0
102 x 85 mm



2I640SW

Intel® Elkhart Lake ATOM® x6413E / J6412
1 x DDR4 SODIMM Max 32GB
2 x HDMI, LVDS/eDP
Touch Screen Controller
2 x Intel 2.5GbE, 2 x USB 3.1, 5 x USB 2.0
4 x RS232/422/485
4 DI / 4 DO
2 x M.2 B Key Type3042, 1 x Nano SIM
110 x 98 mm



ARK-I 2I640PW+DM003

2025 Q3 Product Development timeline

Expansion Card and Modules



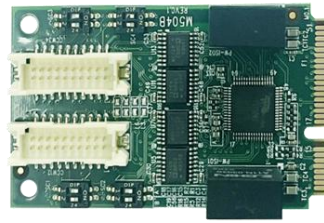
NF226A

M.2 2242 B+M key to
1 x Intel I226IT 2.5GbE



NF226B

M.2 3042 B+M key to
2 x Intel 2.5 GbE



M504B

Mini PCIe to 4* RS232/485/422
(F81504U)

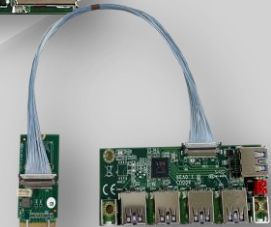


CN073

M.2 B+M Key2280/2242 connector
board for USB HUB



CU006
1 to 4 USB 3.0 HUB



NF212A

M.2 2242 B+M key to
1 x Intel I210IT GbE



NF212B

M.2 3042 B+M key to
2 x Intel GbE



PW505

Isolation power board
with CPC-Ignition on/off control

- 1.5KVDC I/O isolation
- PW505-36: 9–36V in, 12V out, max 60W
- PW505-75: 18–75V in, 12V out, max 60W



ME225-A

Video Capture Card
(from HDMI® device)
4K@30 RAW or
4K@60fps MJPEG



ME225-S

Video Capture Card
(from HDMI® device)
High Speed Micro Coaxial Cable
4K@30 RAW or
4K@60fps MJPEG



RS806 –Riser for 3I140DW
PClex16 to PClex8



RS807 –Riser for 3I140DW
PClex16 to PClex4

LEX SYSTEM with Long-Term Supply

EOL Timeline	2028	2029	2030	2031	2032	2033	2034	2035	2036
Meteor Lake-U/H							Q1		
Raptor Lake-U						Q1			
Tiger Lake-UP3			Q3						
Comet Lake-S			Q2						
Whisky Lake-U						Q3			
Coffee Lake-S 9 th							Q2		
Coffee Lake-S 8 th						Q2			
Kaby Lake-U/S 7 th					Q1				
Skylake-U/S 6 th			Q3						
Elkhart Lake				Q1					
Apollo Lake				Q3					
Bay Trail	Q4								
Jetson Orin			Q1						
i.MX8M Plus									Q1

* Product life span in alignment with Intel's IOTG / NVIDIA modules Life cycle /NXP CPU /AMD longevity.

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